Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **CKB**
2. **RD (1)**
3. **RD (2)**
4. **NC**
5. **Vcc**
6. **NC**
7. **NC**
8. **QC**
9. **QB**
10. **GND**
11. **QD**
12. **QA**
13. **NC**
14. **CHA**

**2 1 14**

**12**

**11**

**10**

**6 7 8 9**

**3**

**(4)**

**5**

**DIE ID**

**B**

**.051”**

**.061”**

**L593**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: L593**

**APPROVED BY: DK DIE SIZE .051” X .061” DATE: 5/7/19**

**MFG: TEXAS INSTRUMENTS THICKNESS .024” P/N: 54LS93**

**DG 10.1.2**

#### Rev B, 7/19/02